



QUALIFICATION PLAN SUMMARY

PCN #: GBNG-24WZVV475

**Date:
July 25, 2019**

**Discontinuance of UNIB assembly site as a qualified location
for selected products available in 8/14/16L PDIP, 20/28L
SSOP, 14/16/20L SOIC, and 48L LQFP packages.**

Purpose: Discontinuance of UNIB assembly site as a qualified location for selected products available in 8/14/16L PDIP, 20/28L SSOP, 14/16/20L SOIC, and 48L LQFP packages.

<u>Misc.</u>	Assembly site	MMT
	BD Number	BDM-002198
	MP Code (MPC)	238017D7XA04
	Part Number (CPN)	MIC2547-2YM
	MSL information	MSL-1
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	48 units
	Reliability Site	MTAI
	CCB No	3911 and 3911.001
<u>Lead-Frame</u>	Paddle size	90 x160 mils
	Material	CDA194
	Surface	Ag Spot plated
	Treatment	None
	Process	Stamped
	Lead-lock	Yes
	Part Number	10101603
	Lead Plating	Matte Tin
<u>Bond Wire</u>	Material	Au
<u>Die Attach</u>	Part Number	8390A
	Conductive	Yes
<u>MC</u>	Part Number	G600V
<u>PKG</u>	PKG Type	SOIC
	Pin/Ball Count	16
	PKG width/size	150 mils
<u>Die</u>	Die Thickness	15 mils
	Die Size	Die 1:83.46 x 39.37 mils Die 2:83.46 x 39.37 mils
	Fab Process (site)	BCD12

Note: The 14L SOIC will qualify by similarity.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	15	0 fails after TC	5	MTAI	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	15	0	5	MTAI	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		MTAI	Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MTAI	
HTSL (High Temp Storage Life)	+175 C for 504 hours. Electrical test pre and post stress at +25°C and hot temp.	45	5	1	50	0	25	MTAI Pre/Post test at UNIS	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C. MSL1 @ 260°C	231	15	3	738	0	15	MTAI Pre/Post test at UNIS	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	MTAI Pre/Post test at UNIS	Spares should be properly identified. Use the parts which have gone through Pre-conditioning. Please decap/ inspect 5 units for anomalies.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail/Accept Qty	Est. Dur. Days	Test Site	Special Instructions
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI Pre/Post test at UNIS	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MTAI Pre/Post test at UNIS	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.